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## Sommario/riassunto

Sintering is the process of forming materials and components from a powder under the action of thermal energy. It is a key materials science subject: most ceramic materials and many specialist metal powder products for use in key industries such as electronics, automotive and aerospace are formed this way. Written by one of the leading experts in the field, this book offers an unrivalled introduction to sintering and sintering processes for students of materials science and engineering, and practicing engineers in industry. The book is unique in providing a complete grounding in the pr